

FNK N-Channel Enhancement Mode Power MOSFET

Description

The FNK2310L uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

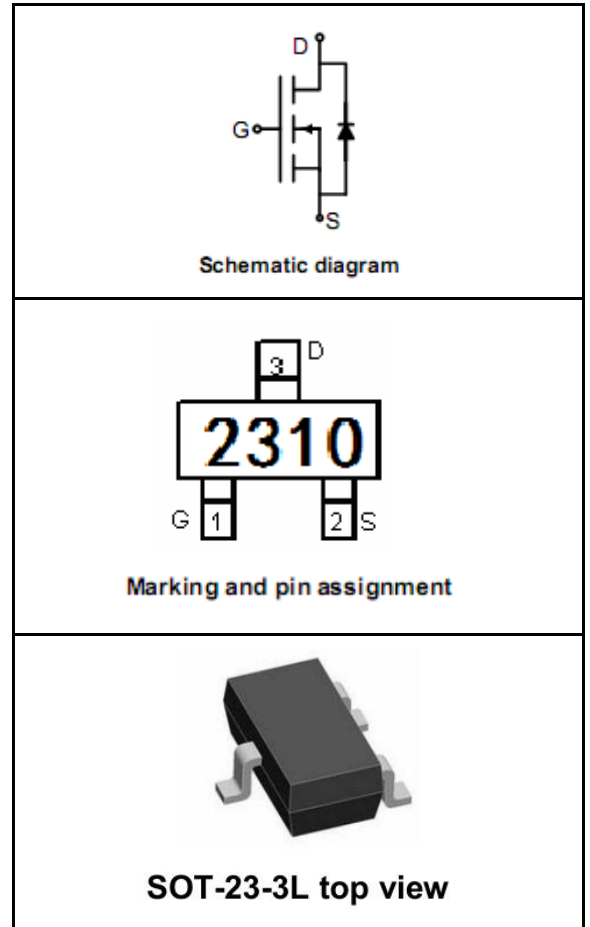
General Features

- $V_{DS} = 20V, I_D = 5A$
 $R_{DS(ON)} < 28m\Omega @ V_{GS} = 4.5V$
 $R_{DS(ON)} < 35m\Omega @ V_{GS} = 2.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery protection
- Load switch
- Power management

PACKAGE MARKING AND ORDERING INFORMATION



Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
FNK2310	FNK2310	SOT-23-3L	Ø180mm	8mm	3000 units

ABSOLUTE MAXIMUM RATINGS($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	$I_D(25^\circ C)$	5	A
	I_{DM}	20	A
Maximum Power Dissipation	P_D	1.25	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	100	$^\circ C/W$
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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	22		V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V			±100	nA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.7	1.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =2.5V, I _D =4.5A		21	35	mΩ
		V _{GS} =4.5V, I _D =5A		18	28	mΩ
Forward Transconductance	g _{FS}	V _{DS} =15V,I _D =5A	25			S
DYNAMIC CHARACTERISTICS (Note4)						
Input Capacitance	C _{ISS}	V _{DS} =10V,V _{GS} =0V, F=1.0MHz		780		PF
Output Capacitance	C _{OSS}			140		PF
Reverse Transfer Capacitance	C _{RSS}			80		PF
SWITCHING CHARACTERISTICS (Note 4)						
Delay Time	t _{d(on)}	V _{DS} =10V,V _{GS} =4.5V,R _{GEN} =6Ω I _D =1A		9		nS
Turn-on Rise Time	t _r			30		nS
Turn-Off Delay Time	t _{d(off)}			35		nS
Turn-Off Fall Time	t _f			10		nS
Total Gate Charge	Q _g	V _{DS} =10V,I _D =5A,V _{GS} =4.5V		11.4		nC
Gate-Source Charge	Q _{gs}			2.3		nC
Gate-Drain Charge	Q _{gd}			2.9		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1A		0.7	1.2	V
Diode Forward Current (Note 2)	I _S				5	A

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on 1in² FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

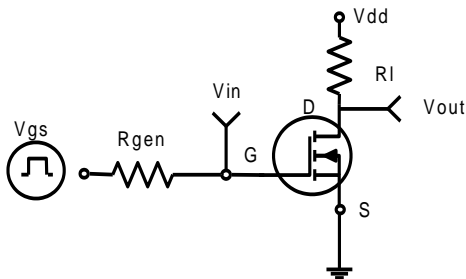


Figure 1: Switching Test Circuit

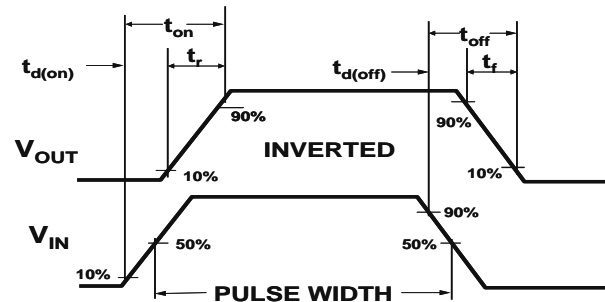


Figure 2: Switching Waveforms

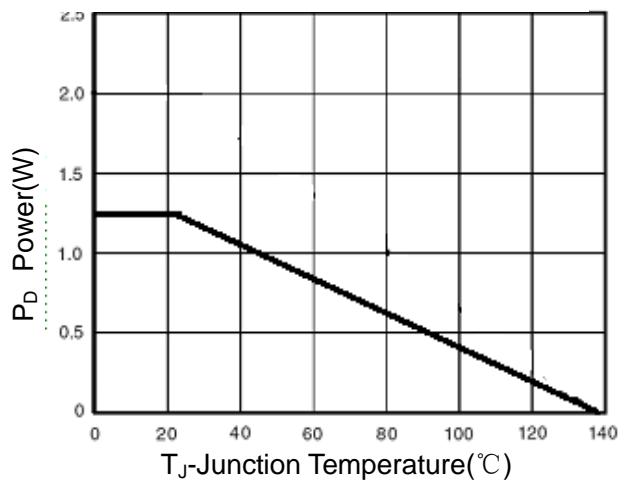


Figure 3 Power Dissipation

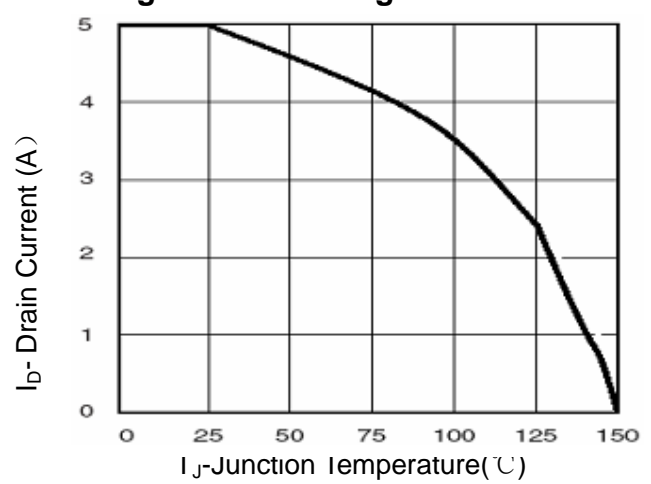


Figure 4 Drain Current

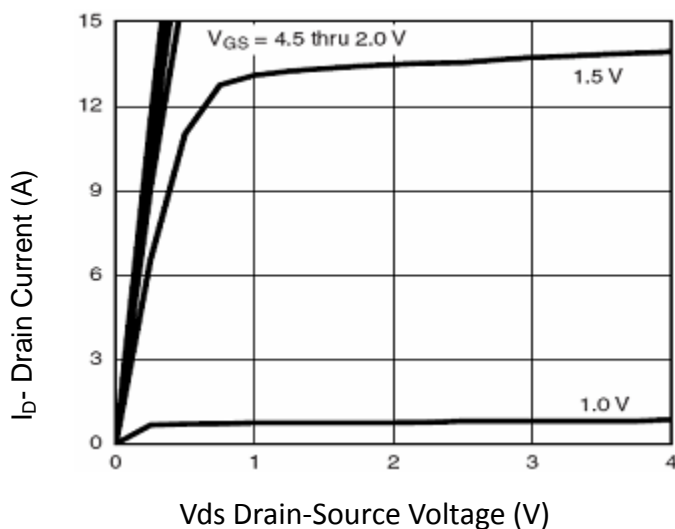


Figure 5 Output Characteristics

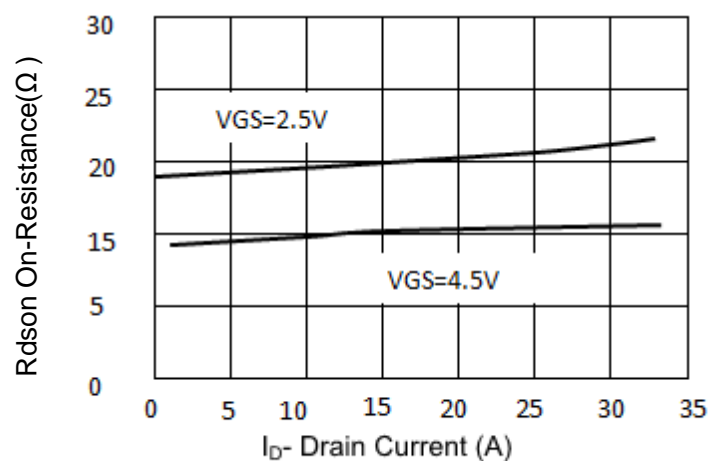
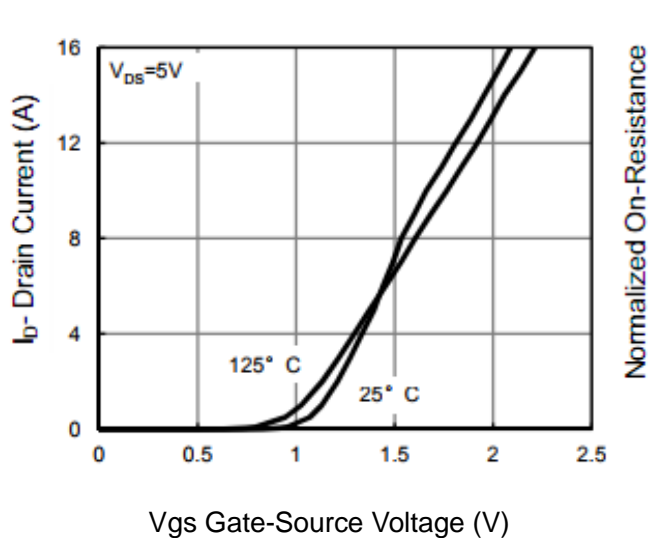
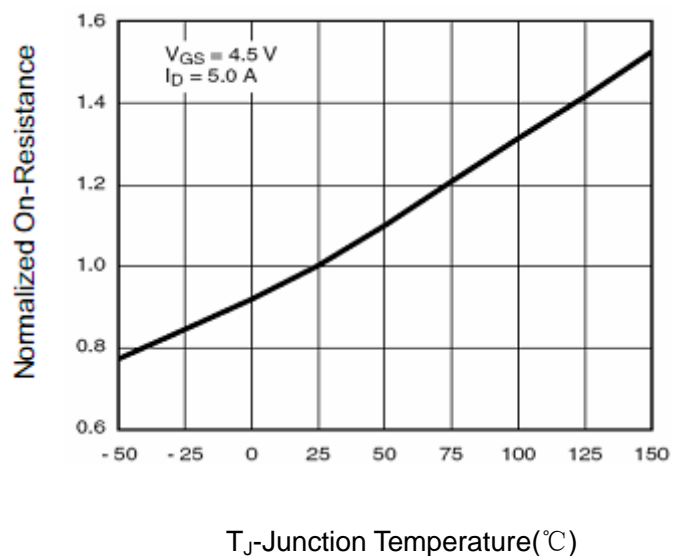
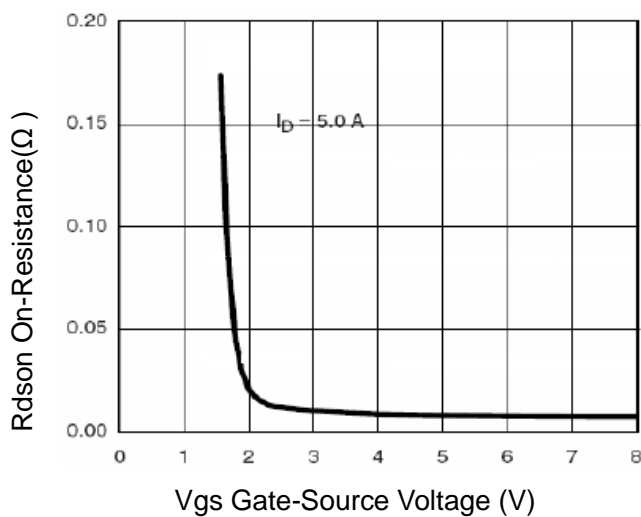
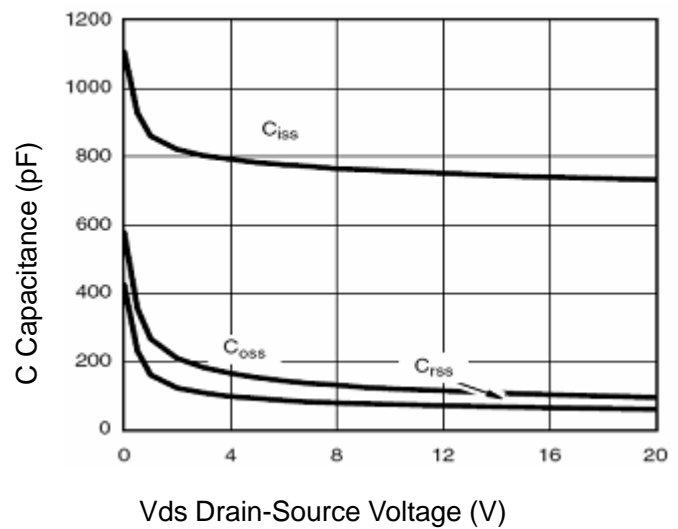
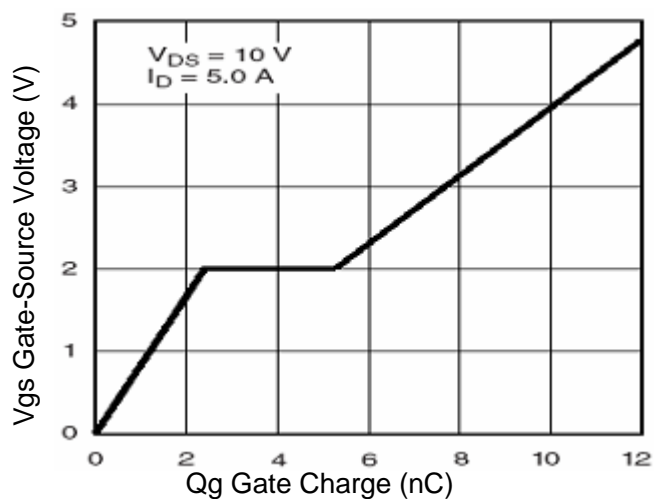
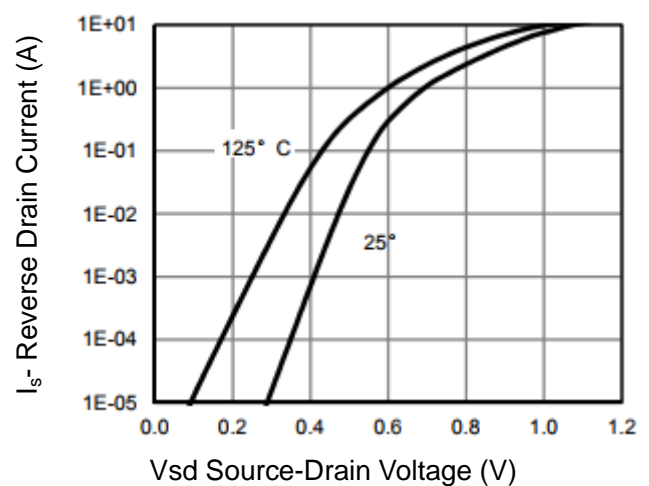


Figure 6 Drain-Source On-Resistance


Figure 7 Transfer Characteristics

Figure 8 Drain-Source On-Resistance

Figure 9 Rdson vs Vgs

Figure 10 Capacitance vs Vds

Figure 11 Gate Charge

Figure 12 Source- Drain Diode Forward

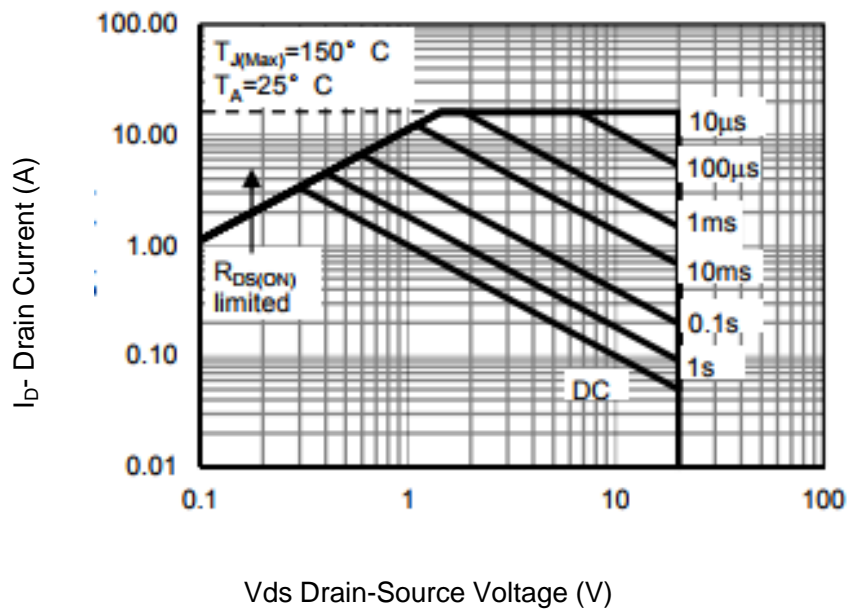


Figure 13 Safe Operation Area

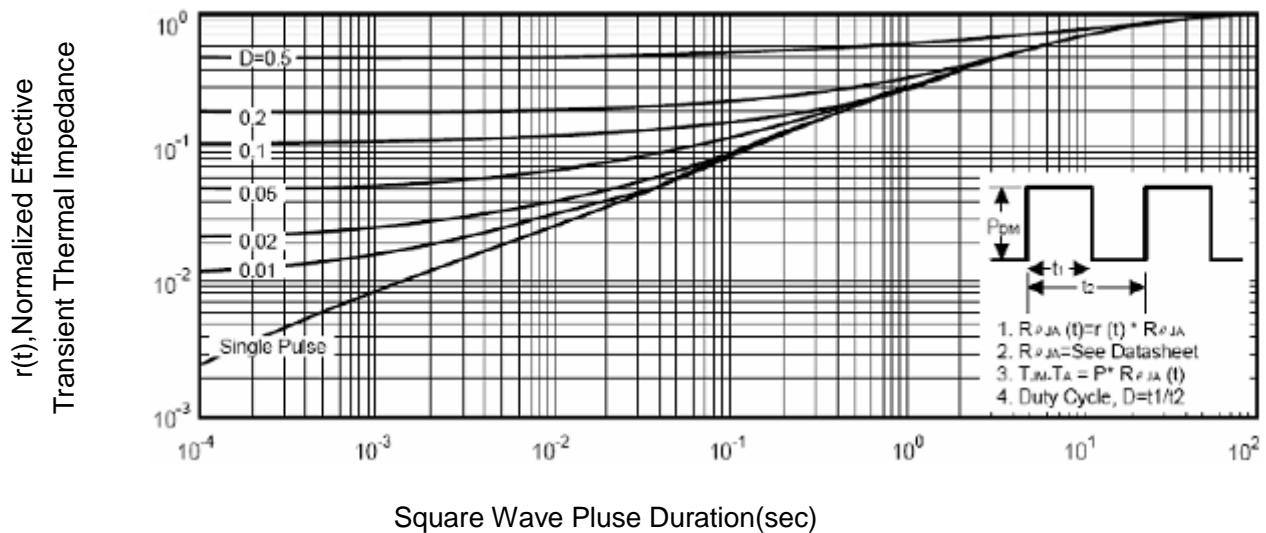
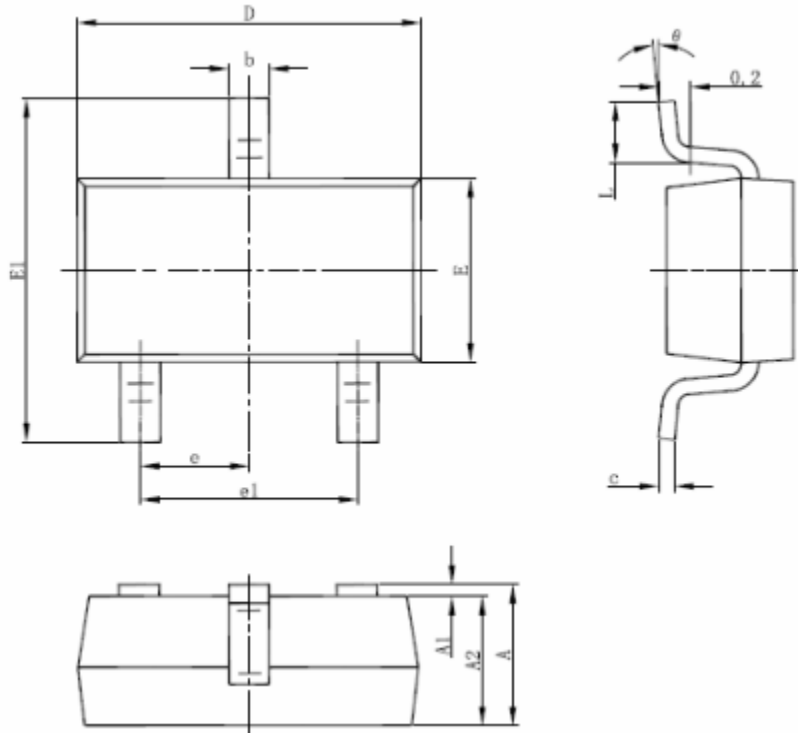


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT-23-3L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Notes

1. All dimensions are in millimeters.
2. Tolerance $\pm 0.10\text{mm}$ (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

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